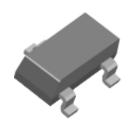
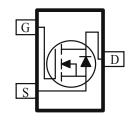
### N-Channel 20V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $r_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

PRODUCT SUMMARY			
<b>V</b> <sub>DS</sub> <b>(V)</b>	$V_{DS}(V)$ $r_{DS(on)}(\Omega)$		
20	$0.058 @V_{CS} = 4.5 V$	2.0	
	$0.082 @V_{CS} = 2.5V$	1.7	

- Low r<sub>DS(on)</sub> provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SC70-3 saves board space
- Fast switching speed
- High performance trench technology





ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C UNLESS OTHERWISE NOTED)						
Parameter Parameter			Maximum Unit			
Drain-Source Voltage		$V_{DS}$	20	V		
Gate-Source Voltage			±8			
C t: D : C .a	T <sub>A</sub> =25°C	τ_	2.0			
Continuous Drain Current <sup>a</sup>	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$	1D	1.7	A		
Pulsed Drain Current <sup>b</sup>		$I_{DM}$	±20			
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	1.6	A		
D. D a	T <sub>A</sub> =25°C	D	0.34	W		
Power Dissipation <sup>a</sup>	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$	гD	0.22			
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Ambient <sup>a</sup>	t <= 5 sec	D	100	00/11/	
	Steady-State	$R_{THJA}$	166	C/W	

#### Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

SPECIFICATIONS (T <sub>A</sub> = 25°C UNLESS OTHERWISE NOTED)							
Danamatan	Carrala al	Task Canditions	Limits			TI	
Parameter	Symbol	Symbol Test Conditions		Тур	Max	Unit	
Static							
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$	0.7			V	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}$			1	uA	
On-State Drain Current <sup>A</sup>	I <sub>D(on)</sub>	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$ $V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	10		10	A	
	*D(on)	$V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$	10		58		
Drain-Source On-Resistance <sup>A</sup>	$r_{DS(on)}$	$V_{GS} = 2.5 \text{ V}, I_D = 1.7 \text{ A}$			82	mΩ	
Forward Tranconductance <sup>A</sup>	$g_{\mathrm{fs}}$	$V_{DS} = 10 \text{ V}, I_D = 2.0 \text{ A}$		11.3		S	
Diode Forward Voltage	$V_{\mathrm{SD}}$	$I_S = 1.6 \text{ A}, V_{GS} = 0 \text{ V}$		0.75		V	
Dynamic <sup>b</sup>	•						
Total Gate Charge	$Q_{g}$			7.5			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$		0.6		nC	
Gate-Drain Charge	$Q_{\mathrm{gd}}$			1.0			
Input Capacitance	$C_{iss}$	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		720		pF	
Output Capacitance	$C_{oss}$			165			
Reverse Transfer Capacitance	$C_{rss}$			60			
Turn-On Delay Time	$t_{d(on)}$			8			
Rise Time	t <sub>r</sub>	$V_{DD} = 10 \text{ V},  R_L = 15 \Omega,  I_D = 1 \text{ A},$ $V_{GEN} = 4.5 \text{ V}$		24		ns	
Turn-Off Delay Time	$t_{d(off)}$			35			
Fall-Time	$t_{\mathrm{f}}$			10		1	

#### Notes

- a. Pulse test:  $PW \le 300us duty cycle \le 2\%$ .
- b. Guaranteed by design, not subject to production testing.

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# Typical Electrical Characteristics (N-Channel)

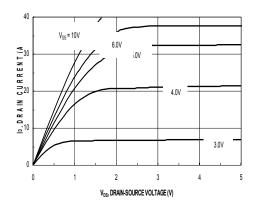


Figure 1. On-Region Characteristics

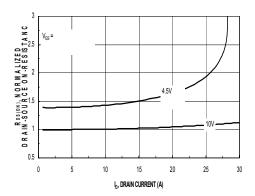


Figure 3. On Resistance Vs Vgs Voltage

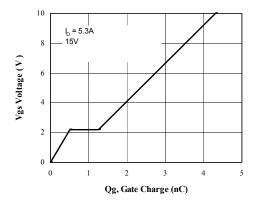


Figure 5. Gate Charge Characteristics

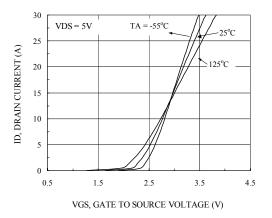


Figure 2. Body Diode Forward Voltage Variation with Source Current and Temperature

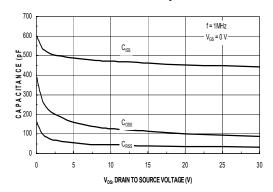


Figure 4. Capacitance Characteristics

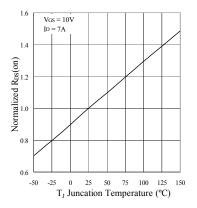


Figure 6. On-Resistance Variation with Temperature

## Typical Electrical Characteristics (N-Channel)

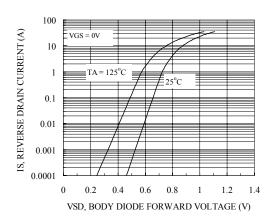


Figure 7. Transfer Characteristics

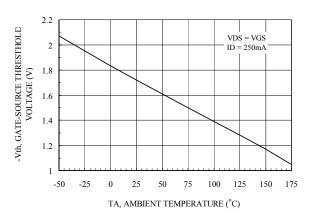


Figure 9. Vth Gate to Source Voltage Vs Temperature

0.2

0.02 0.01

SINGLE PULSE

0.001

0.01

0.1

0.01

0.001

(C)

0.0001

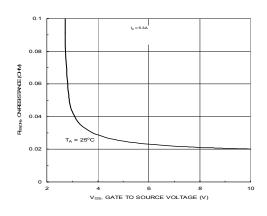


Figure 8. On-Resistance with Gate to Source Voltage

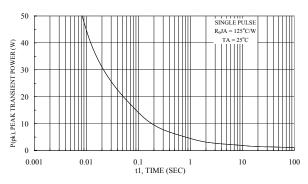


Figure 10. Single Pulse Maximum Power Dissipation

 $T_J - T_A = P * Rq J_{A(t)}$ 

Duty Cycle, D = t1

100

1000

www.freescale.net.cn

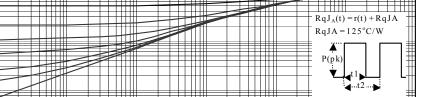


Figure 11. Transient Thermal Response Curve

4

**Normalized Thermal Transient Junction to Ambient** 

t1, TIME (sec)